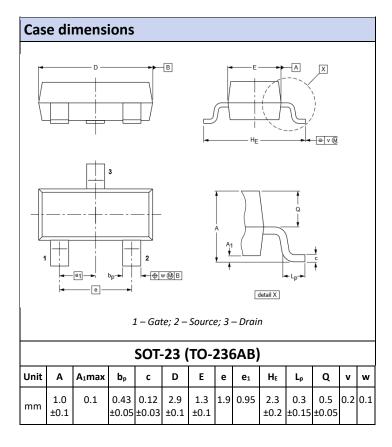


## **P-Channel Enhancement Mode MOSFET**

Primary characteristics			
Symbol	Parameter	Value	Unit
ID	Continuous drain current (@Tc=25°C)	4.8	Α
$V_{\text{DSS}}$	Drain-source voltage	12	٧
R <sub>DSON</sub>	Drain-source ON resistance (@V <sub>GS</sub> =4.5V)	<32	mΩ

# **Application**

- Electronic cigarette
- Load switch



Absolute maximum ratings (T <sub>A</sub> = 25°C unless otherwise noted)					
Characteristic	Symbol	Value	Unit		
Drain-source voltage	V <sub>DS</sub>	12	V		
Gate-source voltage	V <sub>GS</sub>	±12	V		
Continuous drain current	V <sub>GS</sub> =10V, T <sub>C</sub> =25°C	,	4.8	^	
Continuous drain current	V <sub>GS</sub> =10V, T <sub>C</sub> =100°C	I <sub>D</sub>	2.6	Α	
Pulsed drain current 1)	·	I <sub>DM</sub>	16	Α	
Power Dissipation	T <sub>C</sub> =25°C	P <sub>D</sub>	1.0	W	
Thermal resistance junction-ambient	$R_{\Theta JA}$	125	°C/W		
Operating junction temperature range	Tı, Tstg	-55 ~ 150	°C		

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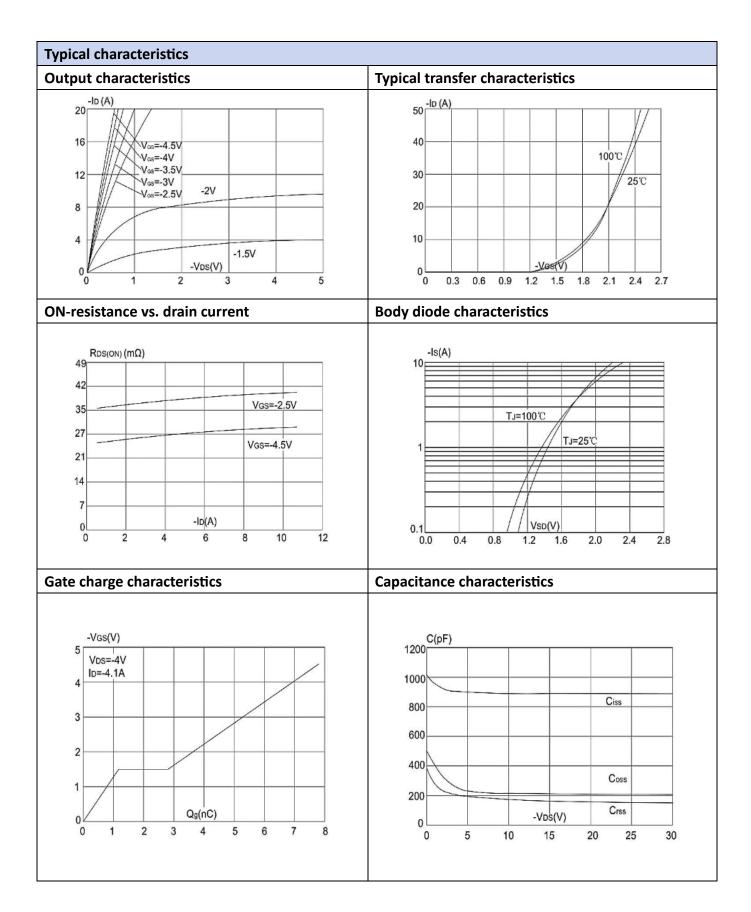
			Value				
Characteristic	Test condition	Symbol	Min.	Тур.	Max.	Unit	
Drain-source breakdown voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	V <sub>(BR)DSS</sub>	12	18	-	V	
Zero gate voltage drain current	V <sub>DS</sub> =12V, V <sub>GS</sub> =0V	I <sub>DSS</sub>	-	-	1.0	μΑ	
Gate to body leakage current	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V	I <sub>GSS</sub>	-	-	±100	nA	
Gate threshold voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250yA	V <sub>GS(TH)</sub>	0.4	0.65	1.0	V	
	V <sub>GS</sub> =4.5V, I <sub>D</sub> =4.1A		-	26	32	mΩ	
Static drain-source on-state resistance 2)	V <sub>GS</sub> =2.5V, I <sub>D</sub> =3.0A	R <sub>DS(ON)</sub>	-	35	53		
Dynamic electrical characteristics							
Characteristic	Test condition		Value			l lmia	
Characteristic	Test condition	Symbol	Min.	Тур.	Max.	Unit	
Input capacitance	V <sub>DS</sub> =4.0V	Ciss	-	905	-		
Output capacitance	V <sub>GS</sub> =0V	Coss	-	210	-	pF	
Reverse transfer capacitance	f=1.0MHz	Crss	-	195	-		
Total gate charge	V <sub>DS</sub> =4.0V	Qg	-	7.8	15		
Gate source charge	V <sub>GS</sub> =4.5V	Qgs	-	1.2	-	nC	
Gate drain ("Miller") charge	I <sub>D</sub> =4.1A	Q <sub>gd</sub>	-	1.6	-		
Switching characteristics							
Characteristic	Took opendition	Symbol	Value			l lmia	
Characteristic	Test condition		Min.	Тур.	Max.	Unit	
Turn on delay time	V <sub>DD</sub> =4.0V	t <sub>d(on)</sub>	-	13	20		
Turn on rise time	I <sub>D</sub> =3.3V	tr	-	35	53		
Turn off delay time	$R_L=1.2\Omega$ $R_G=1.0\Omega$	t <sub>d(off)</sub>	-	32	48	ns	
Turn off fall time	V <sub>GEN</sub> =4.5V	t <sub>f</sub>	-	10	20		
Source drain diode characteristics			l .	l.			
	Test condition	Symbol	Value				
Characteristic			Min.	Тур.	Max.	Unit	
Maximum continuous drain to source diode forward current	-	Is	-	-	4.1	Δ.	
Maximum pulsed drain to source diode forward current	-	I <sub>SM</sub>	-	-	16	А	
Drain-source diode forward voltage	I <sub>S</sub> =4.1A, V <sub>GS</sub> =0V	V <sub>SD</sub>	-	-	1.2	V	
Reverse recovery time	1 444 41/44 4004/ 1/ 01/	t <sub>rr</sub>	-	20	-	ns	
Reverse recovery charge	I <sub>S</sub> =4.1A, dI/dt=100A/μs, V <sub>GS</sub> =0V	Q <sub>rr</sub>	-	9.0	-	nC	

#### Notes:

- 1) The data tested by surface mounted on a 1.0 inch<sup>2</sup> FR-4 board with 2oz copper
- 2) The data tested by pulsed, pulse width ≤300µs, duty cycle ≤2%
- 3) The power dissipation is limited by 150°C junction temperature
- 4) The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation

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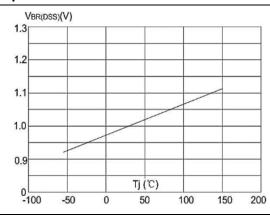




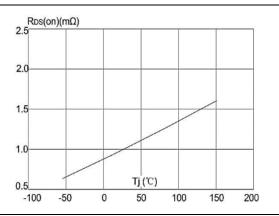


## **Typical characteristics**

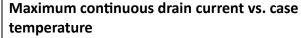
# Normalized breakdown voltage vs. junction temperature

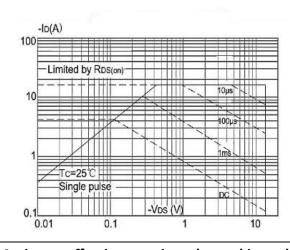


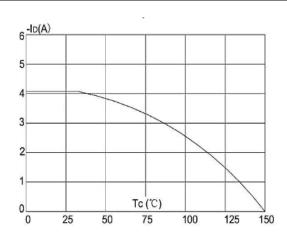
# Normalized on resistance vs. junction temperature



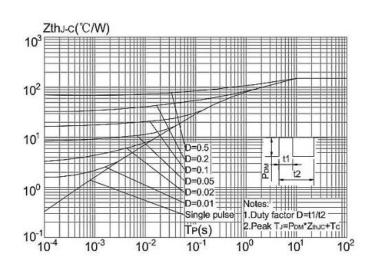
### Maximum safe operating area





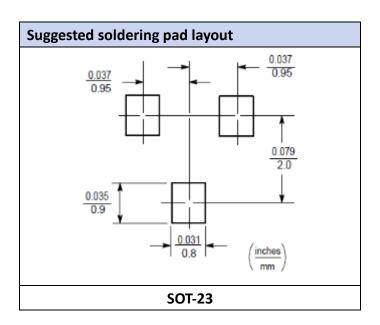


### Maximum effective transient thermal impedance, junction-to-case





Ordering information				
Part Number	Marking	Package	Shipping Quantity	
AKS2311B	2311B	SOT-23	3000 pcs / reel	



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